Abstract

SEMICONDUCTOR PACKAGE AND METHOD OF MOUNTING SEMICONDUCTOR DIE TO OPPOSITE SIDES OF TSV SUBSTRATE

A semiconductor package has a first conductive via formed through a substrate. The substrate with first conductive via is mounted to a first carrier. A first semiconductor die is mounted to a first surface of the substrate. A first encapsulant is deposited over the first die and first carrier. The first carrier is removed. The first die and substrate with the first encapsulant is mounted to a second carrier. A second semiconductor die is mounted to a second surface of the substrate opposite the first surface of the substrate. A second encapsulant is deposited over the second die. The second carrier is removed. A bump is formed over the second surface of the substrate. A conductive layer can be mounted over the first die. A second conductive via can be formed through the first encapsulant and electrically connected to the first conductive via. The semiconductor packages are stackable.
(Fig. 3l)